


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	CRP/19/11174	
1.3 Title of PCI	Alignment of Origin Country information stated on ST Inner and Outer Labels; not related to any changes to the Physical ST Product	
1.4 Product Category	List of 666 Products to be Updated for Origin Country on Inner Labels	
1.5 Issue date	2019-01-17	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	MARSHALL DAVE
2.1.2 Phone	
2.1.3 Email	dave.marshall@st.com
2.2 Change responsibility	
2.2.1 Process Owner	Stefano PEDRETTI
2.2.2 Corporate Quality Manager	Roberto LISSONI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General (Logistic)	Customized labelling (inner or outer)	All Back End Plants

4. Description of change

	Old	New
4.1 Description	Origin Country source for ST Inner and Outer Labels is different, and for some specific cases related to very few products, this could lead to misalignment between ST Inner and Outer Labels.	Origin Country on ST Inner Label is derived from the correct source, which is already used for the ST Outer Labels
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	- Form: No change on product - Fit: No change on product - Function: No change on product. - Reliability, or Processability: NA (Not applicable).	

5. Reason / motivation for change

5.1 Motivation	Origin Country source for ST Inner and Outer Labels is different, and for some specific cases related to very few products, this could lead to misalignment between ST Inner and Outer Labels.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Not Applicable
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7. Timing / schedule

7.1 Date of qualification results	2018-12-07
7.2 Intended start of delivery	2019-02-18
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

11174 Public product.pdf
 11174 11174 PCI 11174 - detail_descr_template_file-Wk02.docx
 11174 11174 PCI 11174-COO on Inner Outer Labels-PQE-Documentation-Wk03.pptx

10. Affected parts

10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	BAL-NRF01D3	
	BALF-NRG-01D3	
	BAT30F4	
	53L0-SATEL-I1	
	BAL-WILC10-01D3	
	BALF-ATM-01E3	
	BALF-NRG-02D3	
	BALF-NRG-02J5	
	BALF-SPI2-01D3	
	BALF-SPI2-02D3	
	ESDALC20-1BF4	
	ESDAVLC5-1BF4	
	ESDV5-1BF4	
	ESDZL5-1F4	
	ESDZV5-1BF4	
	LDBL20D-33R	
	P-NUCLEO-53L0A1	
	P-NUCLEO-53L1A1	
	STPTIC-15L2C4	
	VL53L1X-SATEL	
	VL6180X-SATEL	
	X-NUCLEO-53L0A1	
	X-NUCLEO-53L1A1	
	X-NUCLEO-6180XA1	

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